SINGLE-ENDED ANALOG-INPUT 16-BIT STEREO ANALOG-TO-DIGITAL CONVERTER

FEATURES

- **Dual 16-Bit Monolithic ΔΣ ADC**
- **Single-Ended Voltage Input**
- **Antialiasing Filter Included**
- **64× Oversampling Decimation Filter:**
  Pass-Band Ripple: ±0.05 dB
  Stop-Band Attenuation: –65 dB
- **Analog Performance:**
  THD+N: –88 dB (typical)
  SNR: 93 dB (typical)
  Dynamic Range: 93 dB (typical)
  Internal High-Pass Filter
- **PCM Audio Interface: Left-Justified, I²S**
- **Sampling Rate: 4 kHz to 48 kHz**
- **System Clock: 256 f_S, 384 f_S, or 512 f_S**
- **Single 5-V Power Supply**
- **Small SO-14 Package**

APPLICATIONS

- **DVD Recorders**
- **DVD Receivers**
- **AV Amplifier Receivers**
- **Electric Musical Instruments**

DESCRIPTION

The PCM1801 is a low-cost, single-chip stereo analog-to-digital converter (ADC) with single-ended analog voltage inputs. The PCM1801 uses a delta-sigma modulator with 64 times oversampling, a digital decimation filter, and a serial interface that supports slave mode operation and two data formats. The PCM1801 is suitable for a wide variety of cost-sensitive consumer applications where good performance is required.
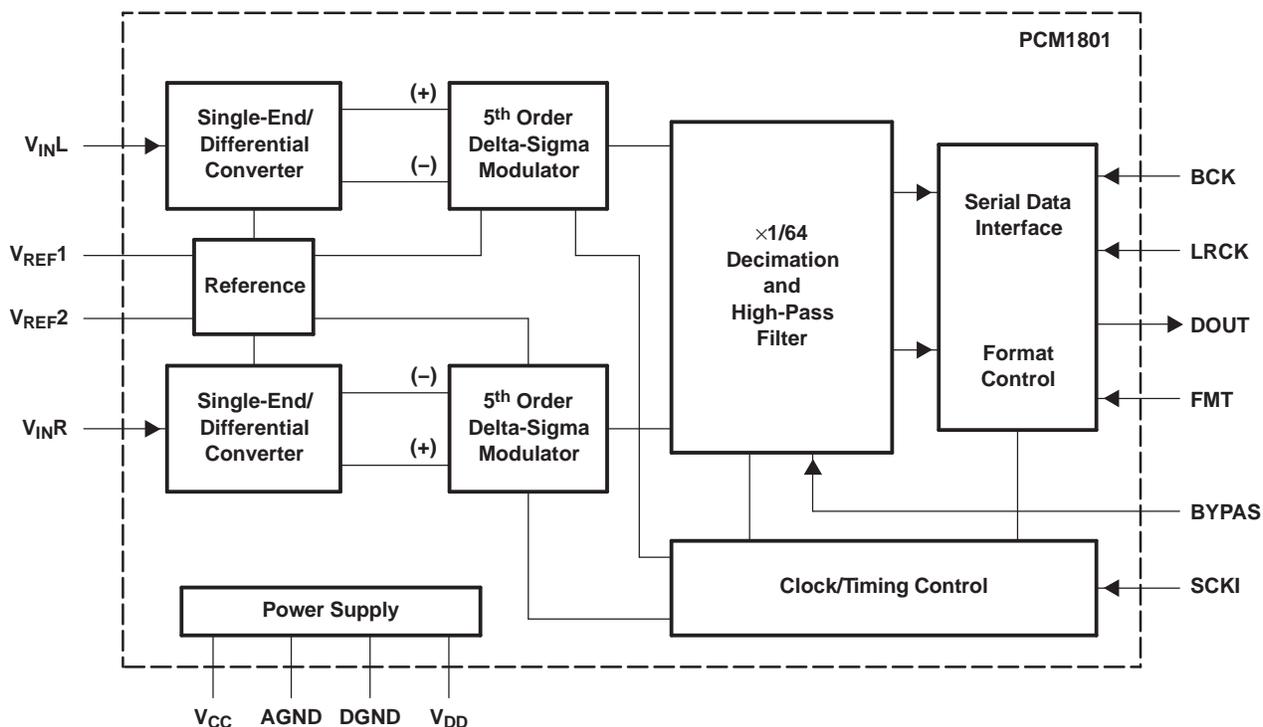
B0004-02

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![Texas Instruments logo]
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This integrated circuit can be damaged by ESD. Texas Instruments recommends that all integrated circuits be handled with appropriate precautions. Failure to observe proper handling and installation procedures can cause damage.

ESD damage can range from subtle performance degradation to complete device failure. Precision integrated circuits may be more susceptible to damage because very small parametric changes could cause the device not to meet its published specifications.

PACKAGE/ORDERING INFORMATION

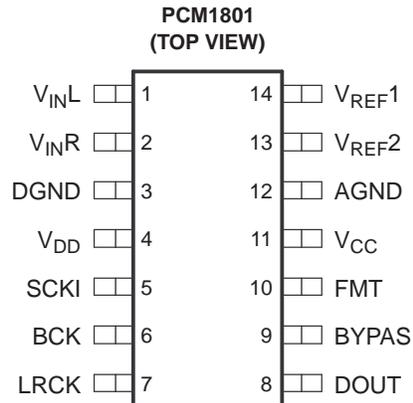| PRODUCT	PACKAGE TYPE	PACKAGE CODE	PACKAGE MARKING	ORDERING NUMBER	TRANSPORT MEDIA	QUANTITY
PCM1801U	14-pin SOIC	D	PCM1801U	PCM1801U	Rails	56
				PCM1801U/2K	Tape and reel	2000

ABSOLUTE MAXIMUM RATINGS

Supply voltage: V_{DD}, V_{CC}	–0.3 V to 6.5 V
Supply voltage differences: V_{DD}, V_{CC}	±0.1 V
GND voltage differences: AGND, DGND	±0.1 V
Digital input voltage	–0.3 V to (V_{DD} + 0.3 V), < 6.5 V
Analog input voltage	–0.3 V to (V_{CC} + 0.3 V), < 6.5 V
Input current (any pin except supplies)	±10 mA
Power dissipation	300 mW
Operating temperature range	–25°C to 85°C
Storage temperature	–55°C to 125°C
Lead temperature, soldering	260°C, 5 s
Package temperature (IR reflow, peak)	235°C

RECOMMENDED OPERATING CONDITIONS

over operating free-air temperature range

		MIN	NOM	MAX	UNIT
Analog supply voltage, V_{CC}		4.5	5	5.5	V
Digital supply voltage, V_{DD}		4.5	5	5.5	V
Analog input voltage, full-scale (–0 dB)			2.828		Vp-p
Digital input logic family			TTL		
Digital input clock frequency	System clock	8.192		24.576	MHz
	Sampling clock	32		48	kHz
Digital output load capacitance			10		pF
Operating free-air temperature, T_A		–25		85	°C

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PIN CONFIGURATION

**PCM1801
(TOP VIEW)**

```
        V_IN L  ┌─┐ 1      14 ┌─┐ V_REF 1
        V_IN R  ┌─┐ 2      13 ┌─┐ V_REF 2
        DGND    ┌─┐ 3      12 ┌─┐ AGND
        V_DD    ┌─┐ 4      11 ┌─┐ V_CC
        SCKI    ┌─┐ 5      10 ┌─┐ FMT
        BCK     ┌─┐ 6       9 ┌─┐ BYPAS
        LRCK    ┌─┐ 7       8 ┌─┐ DOUT
```

P0005-01

Table 1. PIN ASSIGNMENTS

NAME	PIN	I/O	DESCRIPTION	
AGND	12	–	Analog ground	
BCK	6	I	Bit clock input	
BYPAS	9	I	HPF bypass control[1]	L: HPF enabled
				H: HPF disabled
DGND	3	–	Digital ground	
DOUT	8	O	Audio data output	
FMT	10	I	Audio data format[1]	L: MSB-first, left-justified
				H: MSB-first, I^2S
LRCK	7	I	Sampling clock input	
SCKI	5	I	System clock input; 256 f_S, 384 f_S, or 512 f_S	
V_{CC}	11	–	Analog power supply	
V_{DD}	4	–	Digital power supply	
$V_{IN}L$	1	I	Analog input, Lch	
$V_{IN}R$	2	I	Analog input, Rch	
$V_{REF}1$	14	–	Reference 1 decoupling capacitor	
$V_{REF}2$	13	–	Reference 2 decoupling capacitor	

(1) With 100-kΩ typical pulldown resistor

ELECTRICAL CHARACTERISTICS

All specifications at $T_A = 25°C$, $V_{DD} = V_{CC} = 5$ V, $f_S = 44.1$ kHz, 16-bit data, and SYSCLK = 384 f_S, unless otherwise noted.

PARAMETER		TEST CONDITIONS	PCM1801U			UNITS
			MIN	TYP	MAX	
RESOLUTION				16		Bits
DIGITAL INPUT/OUTPUT						
V_{IH}[1]	Input logic level		2			VDC
V_{IL}[1]					0.8	
I_{IN}[2]	Input logic current				±10	µA
I_{IN}[3]					100	
V_{OH}[4]	Output logic level	$I_{OH} = -1.6$ mA	4.5			VDC
V_{OL}[4]		$I_{OL} = 3.2$ mA			0.5	
f_S	Sampling frequency		4	44.1	48	kHz
	System clock frequency	256 f_S	1.024	11.2896	12.288	MHz
		384 f_S	1.536	16.9344	18.432	
		512 f_S	2.048	22.5792	24.576	
DC ACCURACY						
	Gain mismatch, channel-to-channel			±1	±2.5	% of FSR
	Gain error			±2	±5	% of FSR
	Gain drift			±20		ppm of FSR/°C
	Bipolar zero error	High-pass filter bypassed		±2		% of FSR
	Bipolar zero drift	High-pass filter bypassed		±20		ppm of FSR/°C
DYNAMIC PERFORMANCE[5]						
	THD+N	FS (−0.5 dB)		−88	−80	dB
		−60 dB		−90		
	Dynamic range	A-weighted	90	93		dB
	Signal-to-noise ratio	A-weighted	90	93		dB
	Channel separation		87	90		dB
ANALOG INPUT						
	Input range	FS ($V_{IN} = 0$ dB)		2.828		Vp-p
	Center voltage			2.1		V
	Input impedance			30		kΩ
	Antialiasing filter frequency response	−3 dB		150		kHz
DIGITAL FILTER PERFORMANCE						
	Pass band				0.454 f_S	Hz
	Stop band		0.583 f_S			Hz
	Pass-band ripple				±0.05	dB
	Stop-band attenuation		−65			dB
	Delay time (latency)			17.4/f_S		s
	High-pass frequency response	−3 dB		0.019 f_S		mHz

(1) Pins 5, 6, 7, 9, and 10 (SCKI, BCK, LRCK, BYPAS, and FMT)
(2) Pins 5, 6, 7 (SCKI, BCK, LRCK) Schmitt-trigger input
(3) Pins 9, 10 (BYPAS, FMT) Schmitt-trigger input with 100-kΩ typical pulldown resistor
(4) Pin 8 (DOUT)
(5) $f_{IN} = 1$ kHz, using the System Two™ audio measurement system by Audio Precision™ in rms mode with 20-kHz LPF and 400-Hz HPF in the performance calculation.
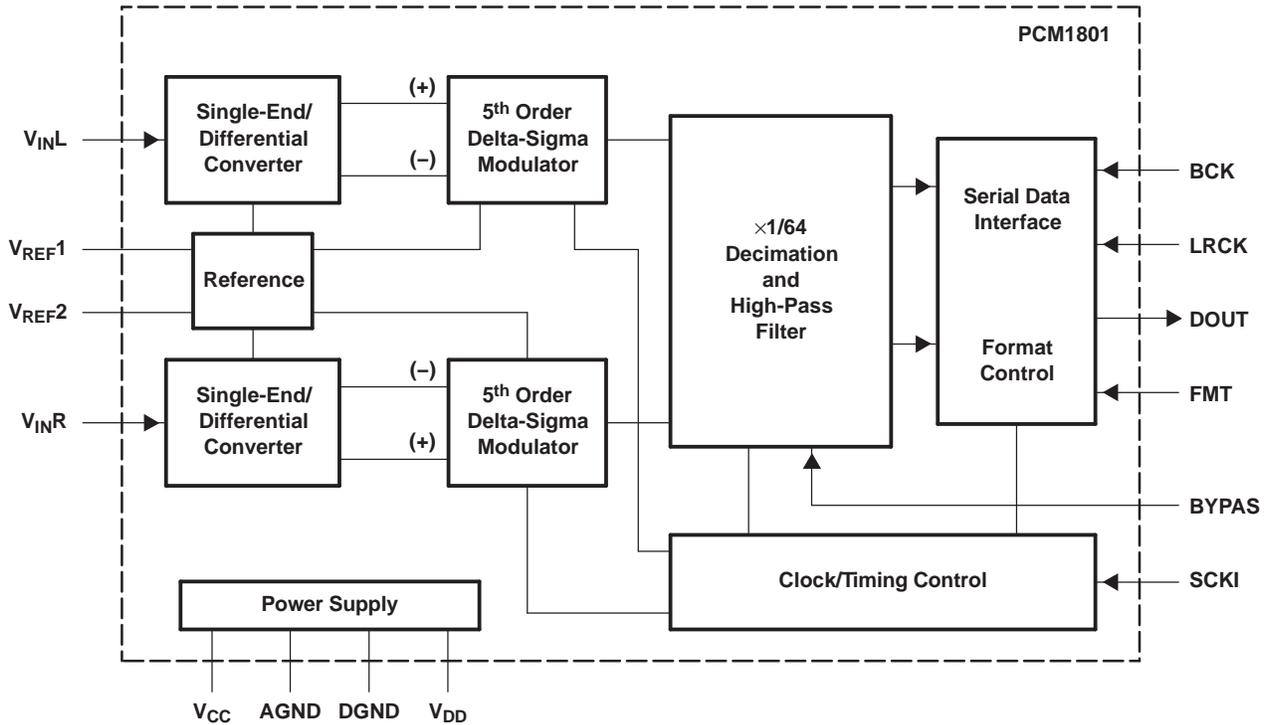
ELECTRICAL CHARACTERISTICS (continued)

All specifications at $T_A = 25°C$, $V_{DD} = V_{CC} = 5$ V, $f_S = 44.1$ kHz, 16-bit data, and SYSCLK = 384 f_S, unless otherwise noted.

PARAMETER		TEST CONDITIONS	PCM1801U			UNITS
			MIN	TYP	MAX	
POWER SUPPLY REQUIREMENTS						
V_{CC}	Voltage range		4.5	5	5.5	VDC
V_{DD}			4.5	5	5.5	
	Supply current [6]	$V_{CC} = V_{DD} = 5$ V		18	24	mA
	Power dissipation	$V_{CC} = V_{DD} = 5$ V		90	120	mW
TEMPERATURE RANGE						
T_A	Operation		−25		85	°C
T_{stg}	Storage		−55		125	°C
$θ_{JA}$	Thermal resistance			100		°C/W

(6)   No load on DOUT (pin 8)

BLOCK DIAGRAM

B0004-02

ANALOG FRONT-END (Single Channel)
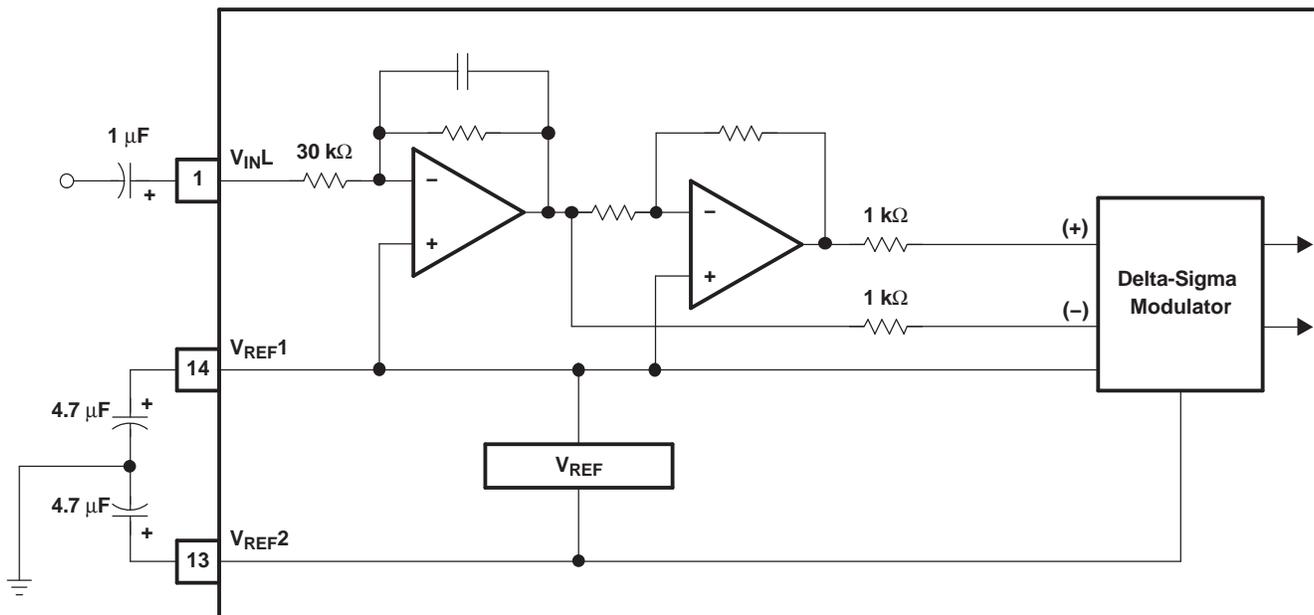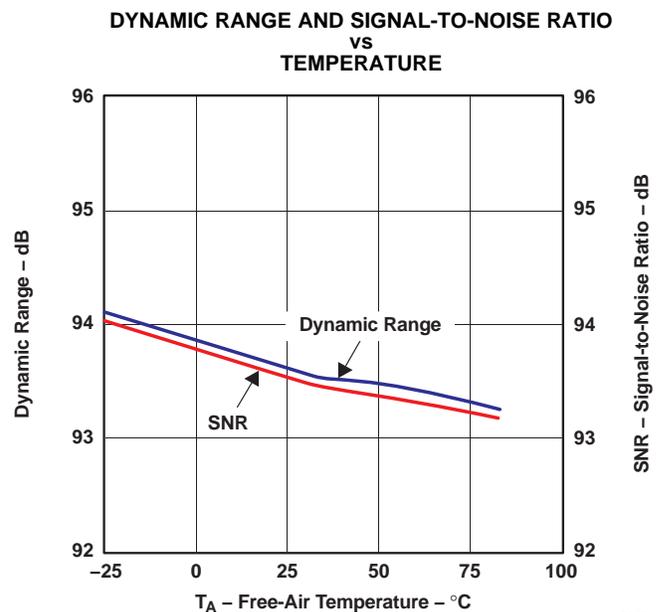

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TYPICAL PERFORMANCE CURVES

All specifications at T_A = 25°C, V_{DD} = V_{CC} = 5 V, f_S = 44.1 kHz, and SYSCLK = 384 f_S, unless otherwise noted

ANALOG DYNAMIC PERFORMANCE

**TOTAL HARMONIC DISTORTION + NOISE
vs
TEMPERATURE**

G001

Figure 1.

**DYNAMIC RANGE AND SIGNAL-TO-NOISE RATIO
vs
TEMPERATURE**
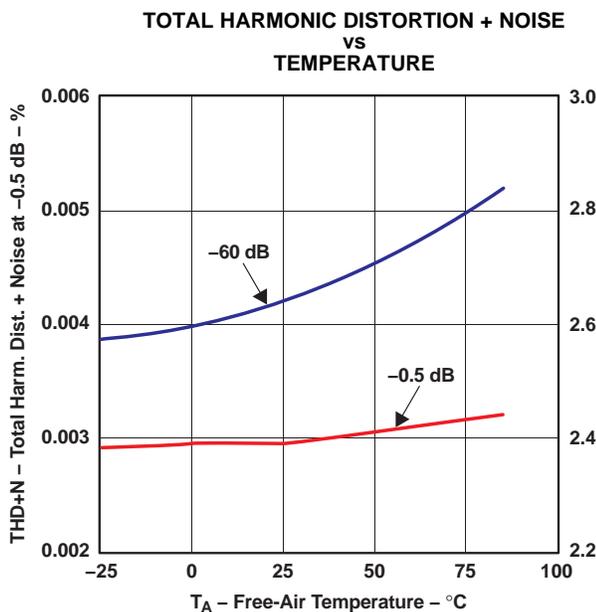
G002

Figure 2.

TYPICAL PERFORMANCE CURVES (continued)

All specifications at T_A = 25°C, V_{DD} = V_{CC} = 5 V, f_S = 44.1 kHz, and SYSCLK = 384 f_S, unless otherwise noted

TOTAL HARMONIC DISTORTION + NOISE
vs
SUPPLY VOLTAGE

Figure 3.

DYNAMIC RANGE AND SIGNAL-TO-NOISE RATIO
vs
SUPPLY VOLTAGE

Figure 4.

TOTAL HARMONIC DISTORTION + NOISE
vs
SAMPLING RATE

Figure 5.

DYNAMIC RANGE AND SIGNAL-TO-NOISE RATIO
vs
SAMPLING RATE
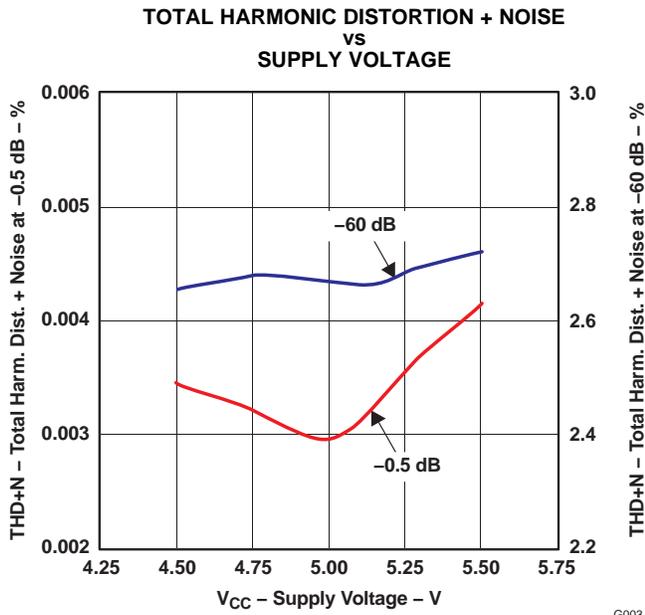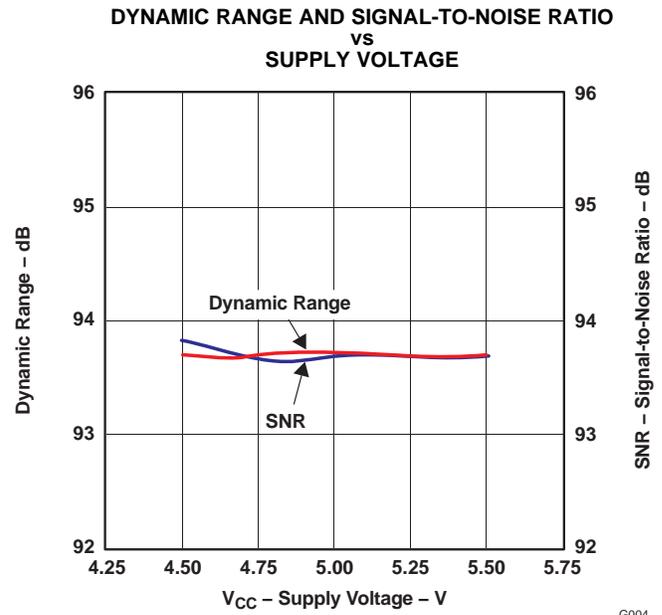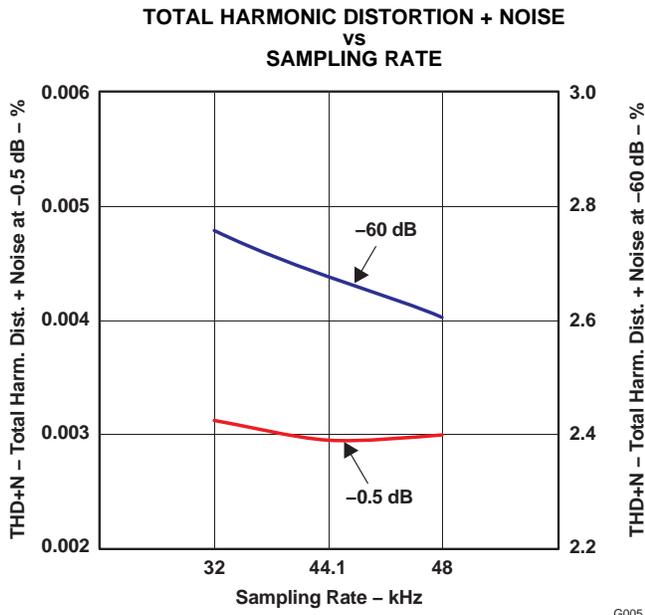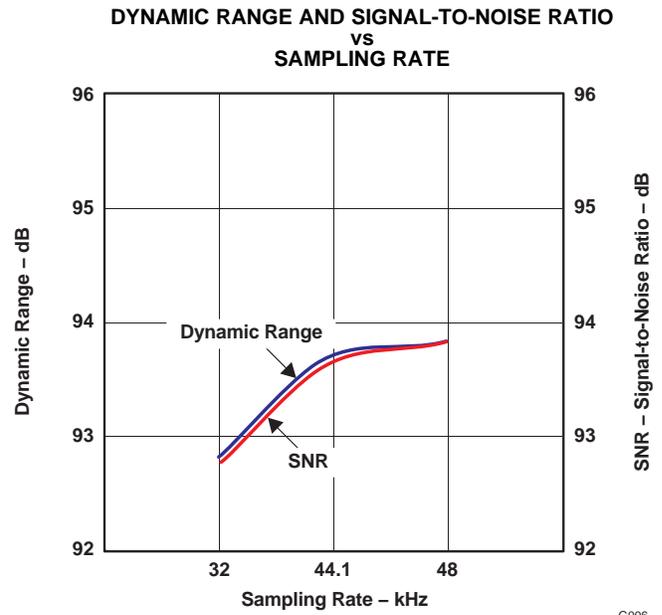
Figure 6.

TYPICAL PERFORMANCE CURVES (continued)

All specifications at $T_A = 25°C$, $V_{DD} = V_{CC} = 5$ V, $f_S = 44.1$ kHz, and SYSCLK = 384 f_S, unless otherwise noted

SUPPLY CURRENT

SUPPLY CURRENT
vs
TEMPERATURE

Figure 7.

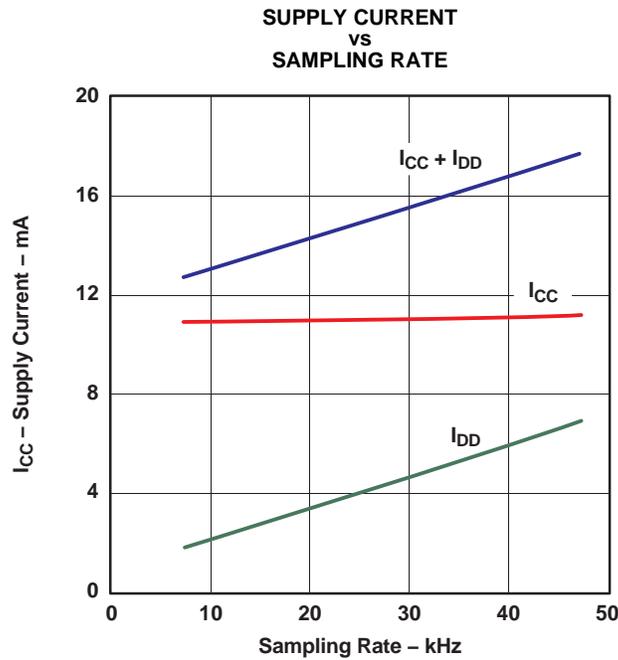SUPPLY CURRENT
vs
SUPPLY VOLTAGE

Figure 8.

SUPPLY CURRENT
vs
SAMPLING RATE
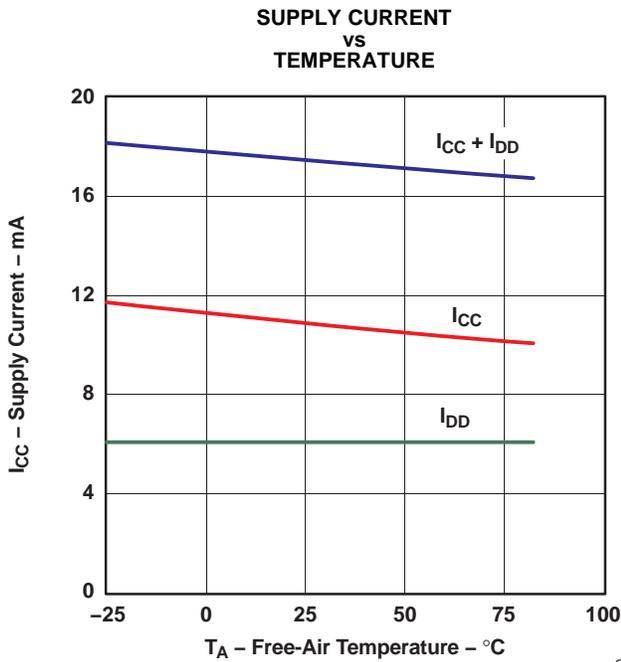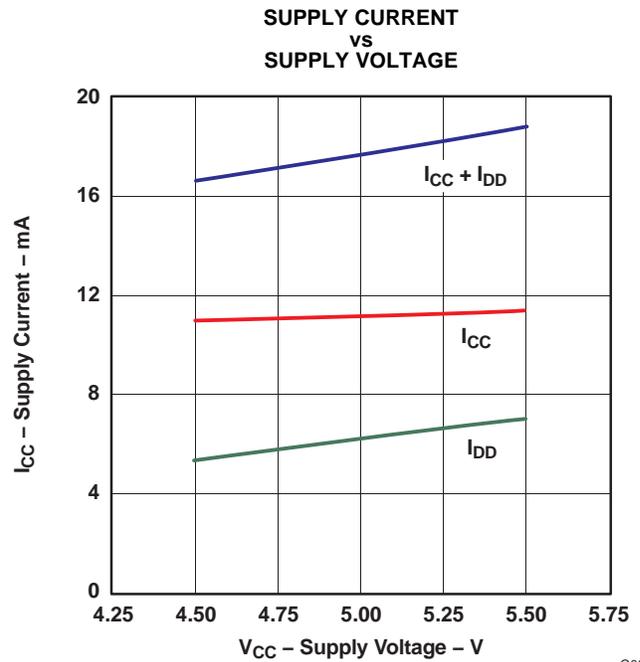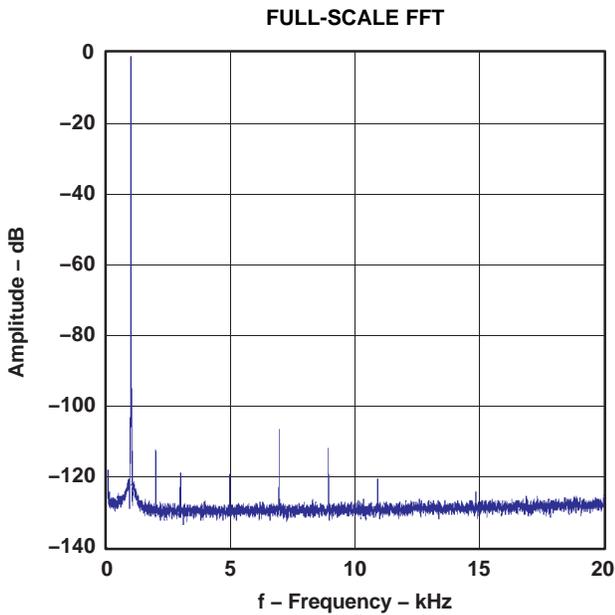

Figure 9.

TYPICAL PERFORMANCE CURVES (continued)

All specifications at T_A = 25°C, V_{DD} = V_{CC} = 5 V, f_S = 44.1 kHz, and SYSCLK = 384 f_S, unless otherwise noted

OUTPUT SPECTRUM
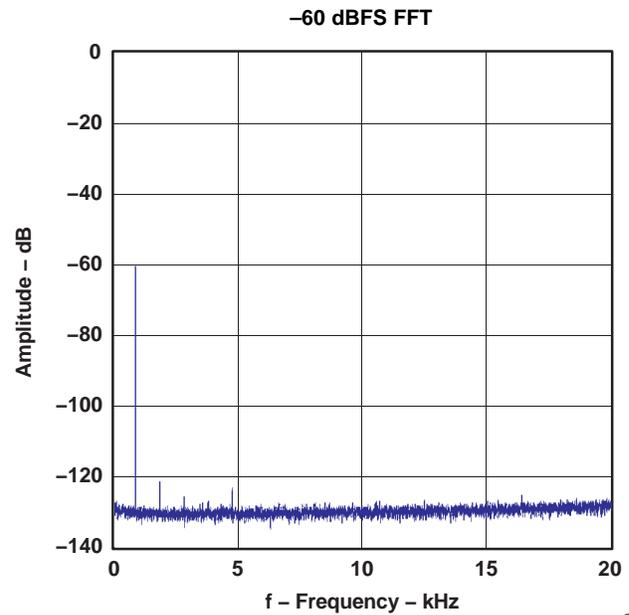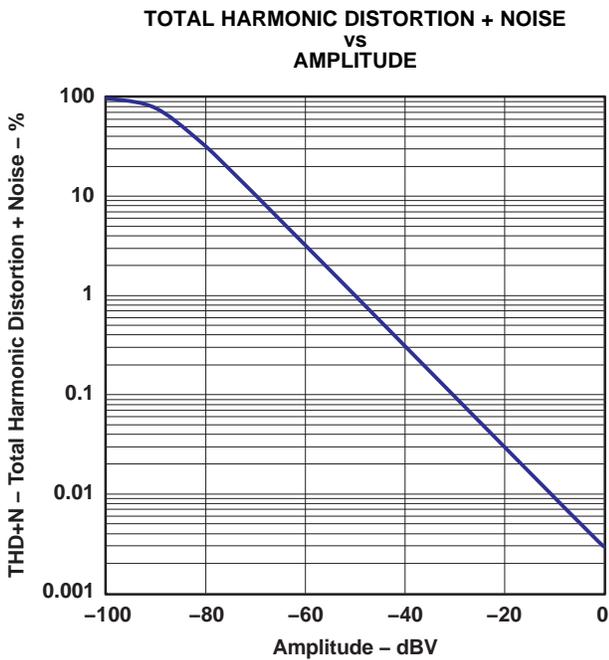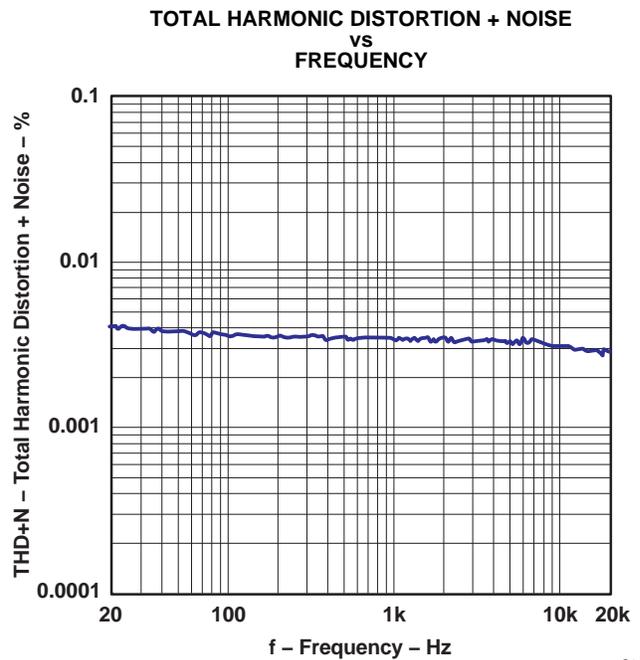
FULL-SCALE FFT

Figure 10.

−60 dBFS FFT

Figure 11.

**TOTAL HARMONIC DISTORTION + NOISE
vs
AMPLITUDE**

Figure 12.

**TOTAL HARMONIC DISTORTION + NOISE
vs
FREQUENCY**

Figure 13.

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TYPICAL PERFORMANCE CURVES (continued)

All specifications at $T_A = 25°C$, $V_{DD} = V_{CC} = 5$ V, $f_S = 44.1$ kHz, and SYSCLK = 384 f_S, unless otherwise noted

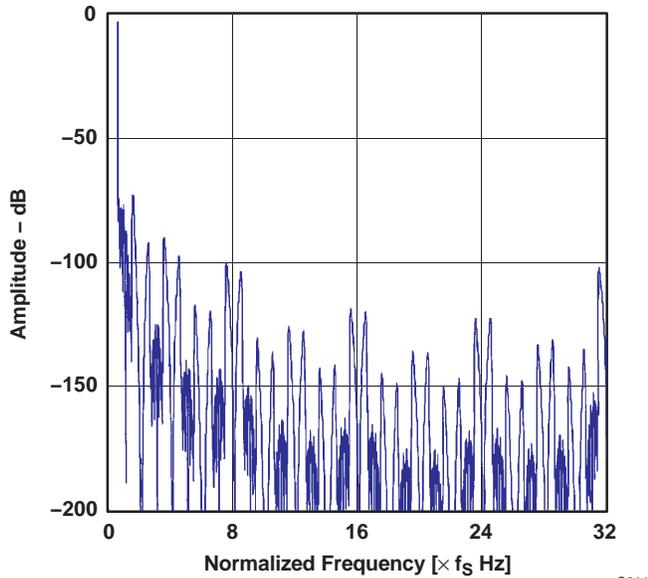### DECIMATION FILTER

OVERALL CHARACTERISTICS

Figure 14.

STOP-BAND ATTENUATION CHARACTERISTICS
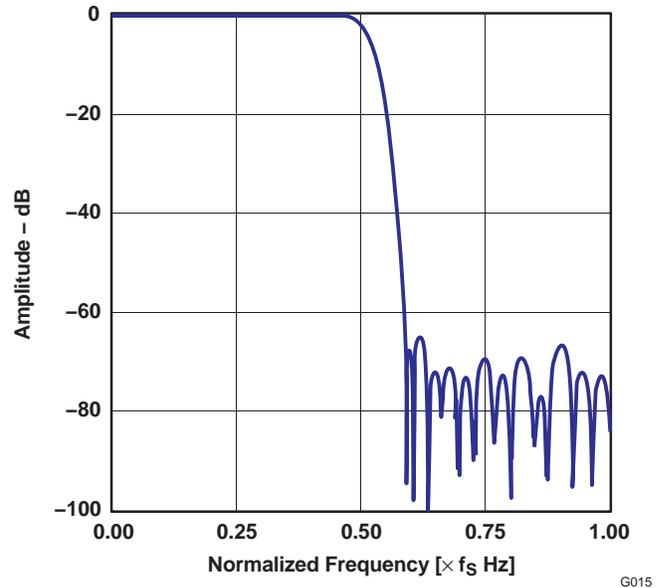
Figure 15.

PASS-BAND RIPPLE CHARACTERISTICS
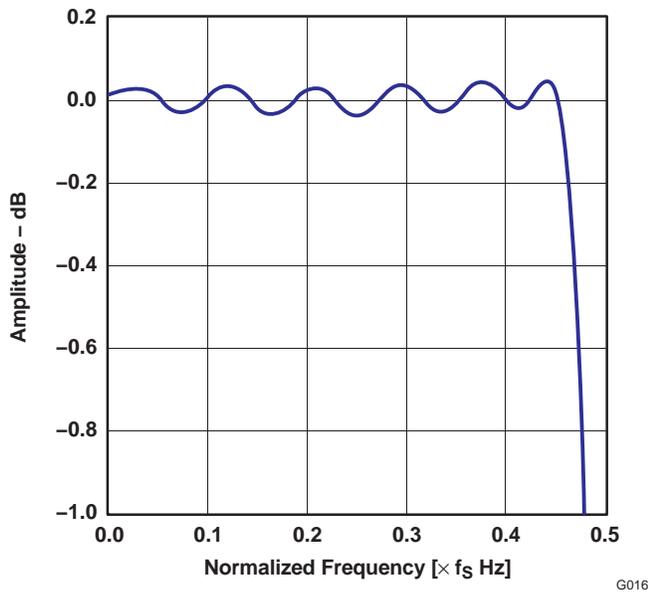
Figure 16.

TRANSITION BAND CHARACTERISTICS

−4.13 dB at 0.5 f_S
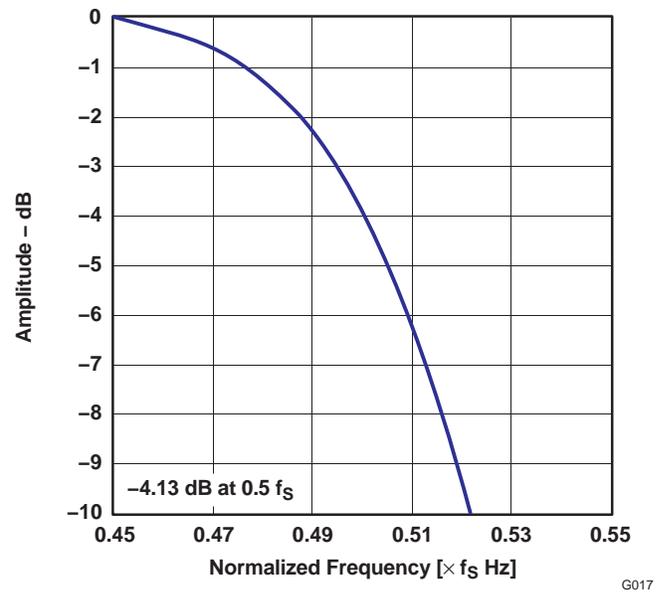
Figure 17.

TYPICAL PERFORMANCE CURVES (continued)

All specifications at T_A = 25°C, V_{DD} = V_{CC} = 5 V, f_S = 44.1 kHz, and SYSCLK = 384 f_S, unless otherwise noted

HIGH-PASS FILTER

HIGH-PASS FILTER RESPONSE

Figure 18.

HIGH-PASS FILTER RESPONSE
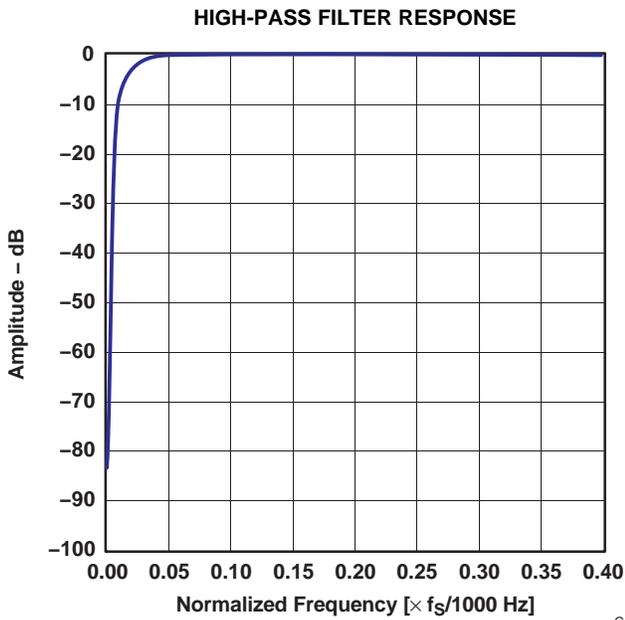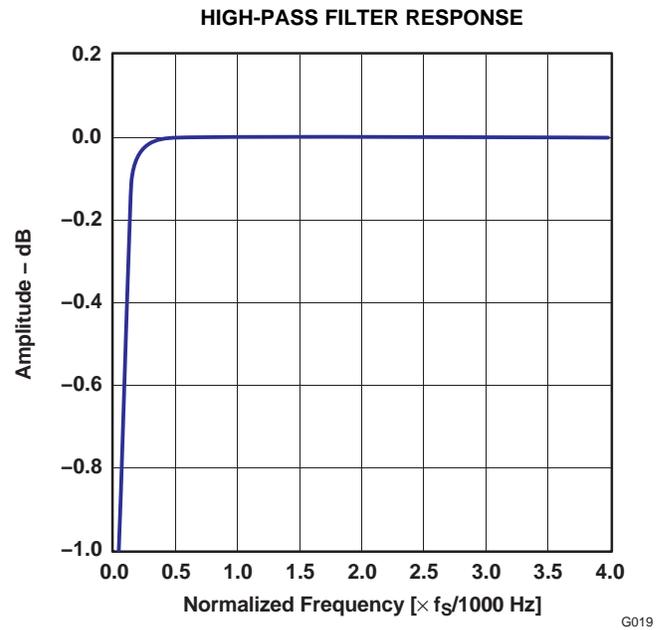
Figure 19.

ANTIALIASING FILTER

**ANTIALIASING FILTER
STOP-BAND CHARACTERISTICS**

Figure 20.

**ANTIALIASING FILTER
PASS-BAND CHARACTERISTICS**

Figure 21.

THEORY OF OPERATION

The PCM1801 consists of a band-gap reference, two channels of a single-to-differential converter, a fully differential 5th-order delta-sigma modulator, a decimation filter (including digital high-pass), and a serial interface circuit. The block diagram illustrates the total architecture of the PCM1801, and the analog front-end diagram illustrates the architecture of the single-to-differential converter and the antialiasing filter. Figure 22 illustrates the architecture of the 5th-order delta-sigma modulator and transfer functions.
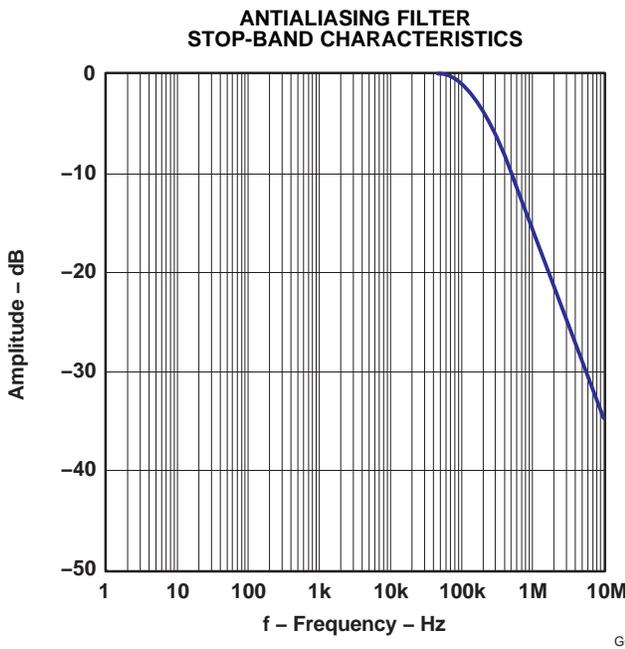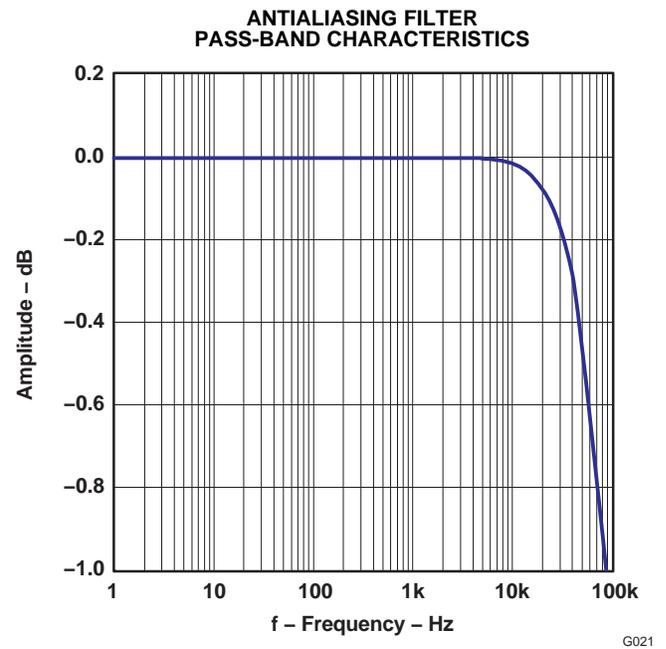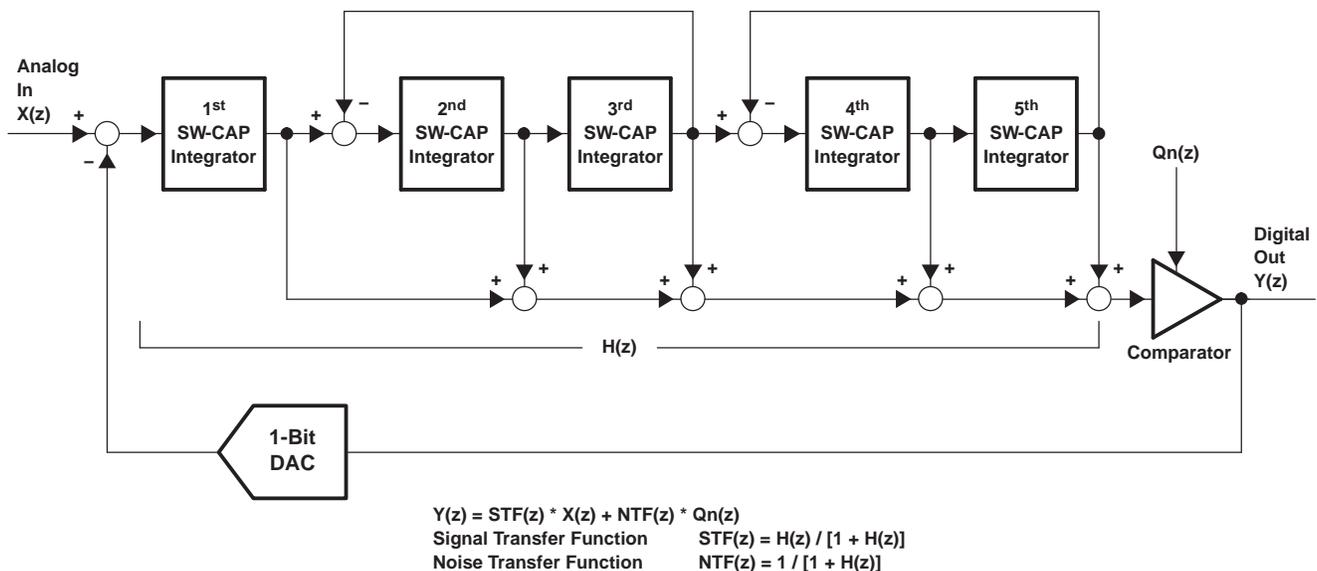
An internal high-precision reference with two external capacitors provides all reference voltages which are required by the converter, and defines the full-scale voltage range of both channels. The internal single-ended to differential voltage converter saves the design, space, and extra parts needed for external circuitry required by many delta-sigma converters. The internal full-differential architecture provides a wide dynamic range and excellent power-supply rejection performance.

The input signal is sampled at a 64× oversampling rate, eliminating the need for a sample-and-hold circuit and simplifying antialias filtering requirements. The 5th-order delta-sigma noise shaper consists of five integrators which use a switched-capacitor topology, a comparator, and a feedback loop consisting of a 1-bit digital-to-analog converter (DAC). The delta-sigma modulator shapes the quantization noise, shifting it out of the audio band in the frequency domain. The high order of the modulator enables it to randomize the modulator outputs, reducing idle tone levels.

The 64-f_S, 1-bit stream from the modulator is converted to 1-f_S, 16-bit digital data by the decimation filter, which also acts as a low-pass filter to remove the shaped quantization noise. The dc components are removed by a digital high-pass filter, and the filtered output is converted to time-multiplexed serial signals through a serial interface which provides flexible serial formats.

$$Y(z) = STF(z) * X(z) + NTF(z) * Qn(z)$$

Signal Transfer Function $\quad STF(z) = H(z) / [1 + H(z)]$

Noise Transfer Function $\quad NTF(z) = 1 / [1 + H(z)]$

B0005-01

Figure 22. Simplified Diagram of the PCM1801 5th-Order Delta-Sigma Modulator

SYSTEM CLOCK

The system clock for the PCM1801 must be either 256 f_S, 384 f_S, or 512 f_S, where f_S is the audio sampling frequency. The system clock must be supplied on SCKI (pin 5).

The PCM1801 also has a system clock detection circuit that automatically senses if the system clock is operating at 256 f_S, 384 f_S, or 512 f_S.

When a 384-f_S or 512-f_S system clock is used, the PCM1801 automatically divides the clock down to 256 f_S internally. This 256-f_S clock is used to operate the digital filter and the modulator. Table 2 lists the relationship of typical sampling frequencies and system clock frequencies. Figure 23 illustrates the system clock timing.

Table 2. System Clock Frequencies

SAMPLING RATE FREQUENCY (kHz)	SYSTEM CLOCK FREQUENCY		
	256 f_s	384 f_s	512 f_s
32	8.1920	12.2880	16.3840
44.1	11.2896	16.9344	22.5792
48	12.2880	18.4320	24.5760
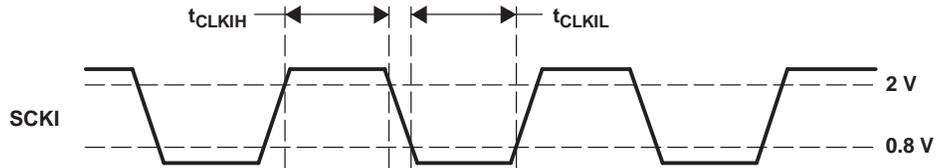
System clock pulse duration, HIGH	$t_{(CLKIH)}$	12 ns (min)
System clock pulse duration, LOW	$t_{(CLKIL)}$	12 ns (min)

Figure 23. System Clock Timing

POWER-ON RESET

The PCM1801 has an internal power-on reset circuit, which initializes (resets) when the supply voltage (V_{CC}/V_{DD}) exceeds 4 V (typical). Because the system clock is used as the clock signal for the reset circuit, the system clock must be supplied as soon as power is applied; more specifically, the device must receive at least three system clock cycles before V_{DD} > 4 V. While V_{CC}/V_{DD} < 4 V (typical) and for 1024 system clock cycles after V_{CC}/V_{DD} > 4 V, the PCM1801 stays in the reset state and the digital output is forced to zero. The digital output is valid 18,436 f_S periods after release from the reset state. Figure 24 illustrates the internal power-on reset timing and the digital output for power-on reset.
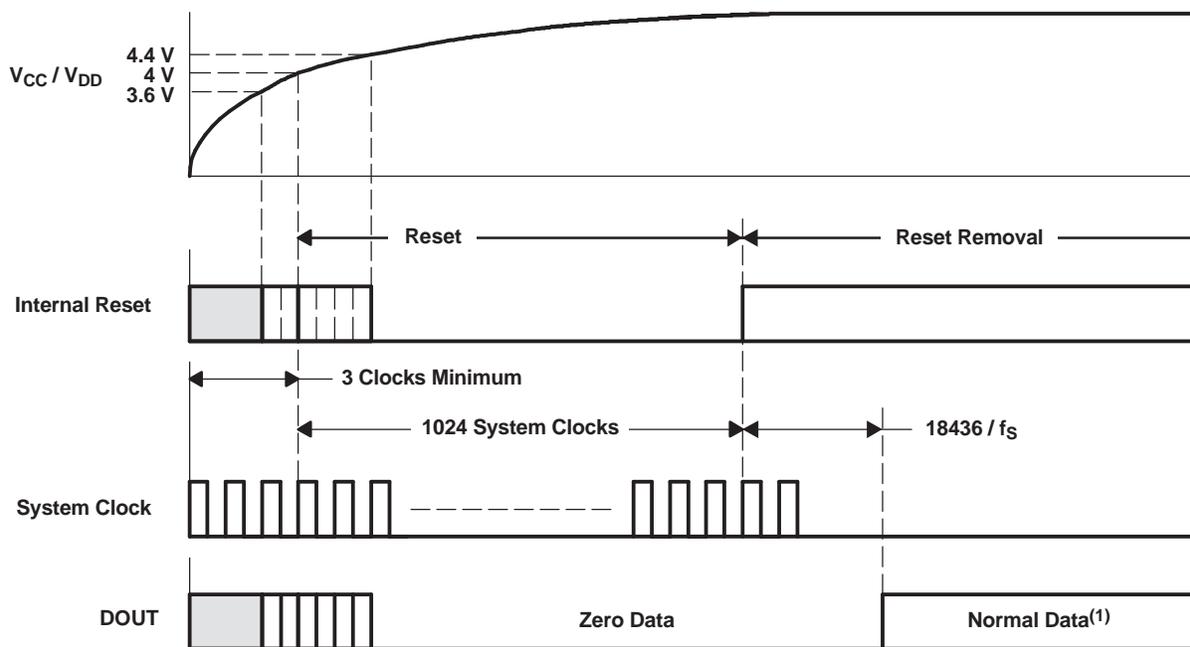
(1) The transient response (exponentially attenuated signal from ±0.2% dc of FSR with a 200-ms time constant) appears initially.

Figure 24. Internal Power-On Reset Timing

SERIAL AUDIO DATA INTERFACE

The PCM1801 interfaces the audio system through BCK (pin 6), LRCK (pin 7), and DOUT (pin 8).

The PCM1801 accepts 64-BCK/LRCK, 48-BCK/LRCK (only for a 384-f_S system clock) or 32-BCK/LRCK format for the left-justified format. And the PCM1801 accepts the 64-BCK/LRCK or 48-BCK/LRCK format (only for a 384-f_S system clock) for I^2S format.

DATA FORMAT

The PCM1801 supports two audio data formats in slave mode, which are selected by the FMT control input (pin 10) as shown in Table 3. Figure 25 illustrates the data format. If the application system cannot ensure an effective system clock prior to power up of the PCM1801, the FMT pin must be held LOW until the power-on reset sequence is completed. In this case, if the I^2S format (FMT = HIGH) is required in the application, FMT can be set HIGH after the power-on reset sequence is completed.

Table 3. Data Format

FMT	DATA FORMAT
0 (L)	16-bit, left-justified
1 (H)	16-bit, I^2S

FMT = L

16-Bit, MSB-First, Left-Justified
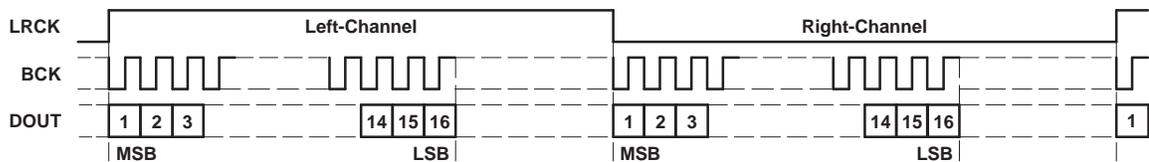
FMT = H

16-Bit, MSB-First, I^2S

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Figure 25. Audio Data Format

INTERFACE TIMING

Figure 26 illustrates the interface timing.

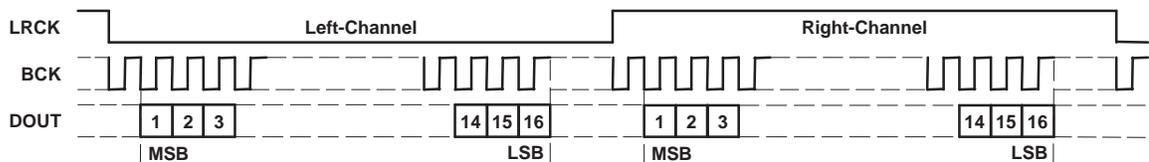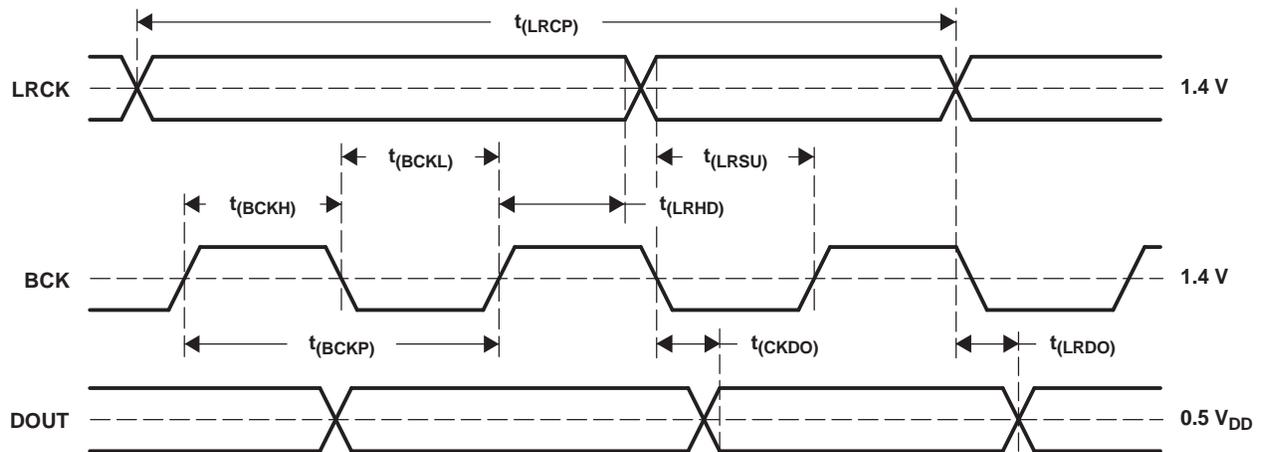| DESCRIPTION	SYMBOL	MIN	TYP	MAX	UNITS
BCK period	$t_{(BCKP)}$	300			ns
BCK pulse duration, HIGH	$t_{(BCKH)}$	120			ns
BCK pulse duration, LOW	$t_{(BCKL)}$	120			ns
LRCK setup time to BCK rising edge	$t_{(LRSU)}$	80			ns
LRCK hold time to BCK rising edge	$t_{(LRHD)}$	40			ns
LRCK period	$t_{(LRCP)}$	20			μs
Delay time, BCK falling edge to DOUT valid	$t_{(CKDO)}$	−20		40	ns
Delay time, LRCK edge to DOUT valid	$t_{(LRDO)}$	−20		40	ns
Rising time of all signals	$t_{(RISE)}$			20	ns
Falling time of all signals	$t_{(FALL)}$			20	ns

NOTE: Timing measurement reference level is $(V_{IH} + V_{IL})/2$. Rising and falling time is measured from 10% to 90% of the I/O signal swing. Load capacitance of the DOUT signal is 20 pF.

Figure 26. Audio Data Interface Timing

SYNCHRONIZATION WITH DIGITAL AUDIO SYSTEM

The PCM1801 operates with LRCK synchronized to the system clock (SCKI). The PCM1801 does not require a specific phase relationship between LRCK and SCKI, but does require the synchronization of LRCK and SCKI. If the relationship between LRCK and SCKI changes more than 6 bit clocks (BCK) during one sample period due to LRCK or SCKI jitter, internal operation of the ADC halts within $1/f_S$ and the digital output is forced to BPZ until resynchronization between LRCK and SCKI is completed. In case of changes less than 5 bit clocks (BCK), resynchronization does not occur and the previously described digital output control and discontinuity do not occur. Figure 27 illustrates the ADC digital output for lost synchronization and resynchronization. During undefined data, some noise may be generated in the audio signal. Also, the transition of normal to undefined data and undefined or zero data to normal makes a discontinuity of data on the digital output and may generate some noise in the audio signal.
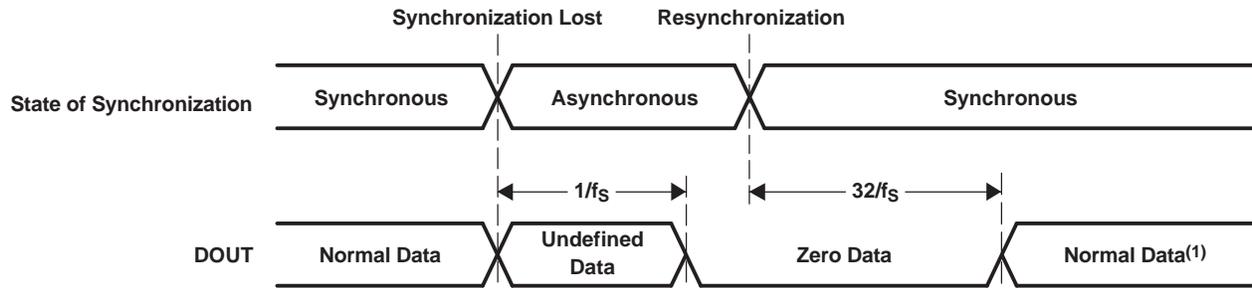
T0020-02

(1) The transient response (exponentially attenuated signal from ±0.2% dc of FSR with 200-ms time constant) appears initially.

Figure 27. ADC Digital Output for Loss of Synchronization and Re-Synchronization

HPF Bypass Control

The built-in function for dc component rejection can be bypassed by BYPAS (pin 9) control (see Table 4). In bypass mode, the dc component of the input analog signal, the internal dc offset, etc., are also converted and output in the digital output data.

Table 4. HPF Bypass Control

BYPAS	HIGH-PASS FILTER (HPF) MODE
Low	Normal (dc cut) mode
High	Bypass (through) mode

APPLICATION INFORMATION

BOARD DESIGN AND LAYOUT CONSIDERATIONS

V_{CC}, V_{DD} PINS

The digital and analog power supply lines to the PCM1801 should be bypassed to the corresponding ground pins with both 0.1-µF ceramic and 10-µF tantalum capacitors as close to the pins as possible to maximize the dynamic performance of the ADC. Although the PCM1801 has two power lines to maximize the potential of dynamic performance, using one common power supply is recommended to avoid unexpected power supply problems, such as latch-up due to power supply sequencing.

AGND, DGND PINS

To maximize the dynamic performance of the PCM1801, the analog and digital grounds are not internally connected. These points should have low impedance to avoid digital noise feedback into the analog ground. They should be connected directly to each other under the PCM1801 package to reduce potential noise problems.

V_{IN} PINS

A 1.0-µF tantalum capacitor is recommended as an ac-coupling capacitor, which establishes a 5.3-Hz cutoff frequency. If a higher full-scale input voltage is required, the input voltage range can be increased by adding a series resistor to the V_{IN} pins.

V_{REF} PINS

To ensure low source impedance, 4.7-µF tantalum capacitors are recommended from $V_{REF}1$ to AGND and from $V_{REF}2$ to AGND. These capacitors should be located as close as possible to the $V_{REF}1$ and $V_{REF}2$ pins to reduce dynamic errors on the ADC references.

APPLICATION INFORMATION (continued)

DOUT PIN

The DOUT pin has a large load-drive capability, but locating a buffer near the PCM1801 and minimizing load capacitance is recommended in order to minimize the digital-analog crosstalk and maximize the dynamic performance of the ADC.

FMT PIN

In general, the FMT pin is used for audio data format selection by tying up DGND or V_{DD} in accordance with interface requirements. If the application system cannot ensure an effective system clock prior to power up of the PCM1801 when I²S format is required, then the FMT pin must be set HIGH after the power-on reset sequence. This input control can be accomplished easily by connecting a C-R delay circuit with a delay time greater than 1 ms to the FMT pin.

SYSTEM CLOCK

The quality of the system clock can influence dynamic performance in the PCM1801. The duty cycle, jitter, and threshold voltage at the system clock input pin must be carefully managed. When power is supplied to the part, the system clock, bit clock (BCK), and word clock (LRCK) should also be supplied simultaneously. Failure to supply the audio clocks results in a power dissipation increase of up to three times normal dissipation and may degrade long-term reliability if the maximum power dissipation limit is exceeded.

TYPICAL CIRCUIT CONNECTION DIAGRAM

Figure 28 is a typical connection diagram illustrating a circuit for which the input HPF cutoff frequency is about 5 Hz.
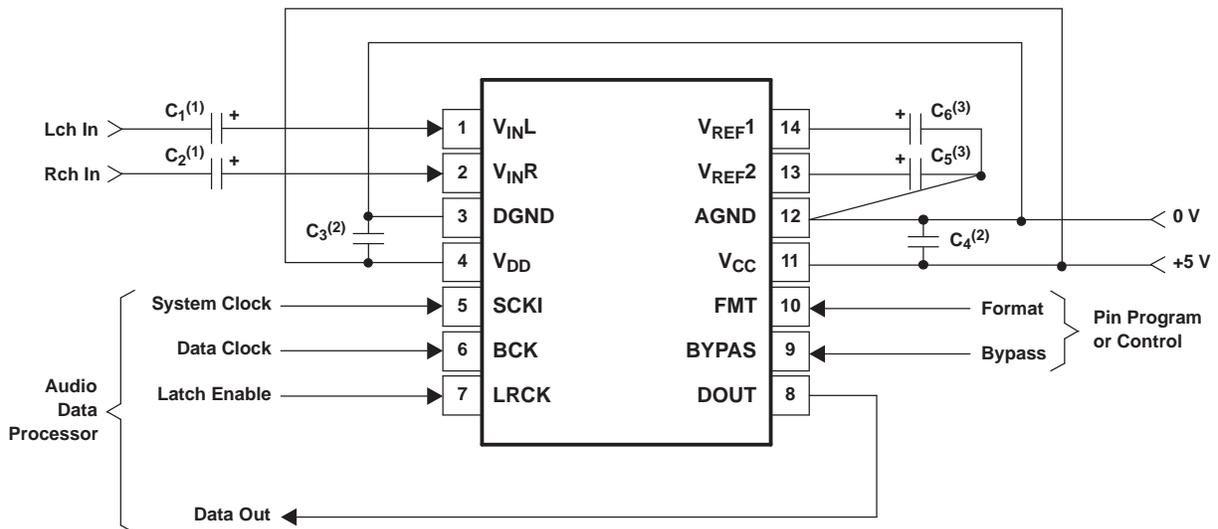
S0013-01

(1) C1 and C2: A 1-μF capacitor gives a 5.3-Hz (τ = 1 μF * 30 kΩ) cutoff frequency for the input HPF in normal operation and requires a power-on setting time of 30 ms at power up.

(2) C3 and C4: Bypass capacitors, 0.1-μF ceramic and 10-μF tantalum or aluminum electrolytic, depending on layout and power supply

(3) C5 and C6: 4.7-μF tantalum or aluminum electrolytic capacitors

Figure 28. Typical Circuit Connection

![Texas Instruments logo]

PACKAGING INFORMATION

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead/Ball Finish	MSL Peak Temp (3)	Op Temp (°C)	Device Marking (4/5)	Samples
PCM1801U	NRND	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM		PCM1801U	
PCM1801U/2K	NRND	SOIC	D	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM		PCM1801U	
PCM1801U/2KG4	NRND	SOIC	D	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM		PCM1801U	
PCM1801UG4	NRND	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM		PCM1801U	

(1) The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

(3) MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

(4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.

(5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.

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D (R−PDSO−G14) PLASTIC SMALL OUTLINE

0.344 (8,75)
0.337 (8,55)
C

14   8

0.244 (6,20)
0.228 (5,80)

0.157 (4,00)
0.150 (3,80)
D

1   7

Pin 1
Index Area

0.050 (1,27)

0.020 (0,51)
0.012 (0,31)

⊕ 0.010 (0,25) M

0.069 (1,75) Max

0.010 (0,25)
0.004 (0,10)

0.010 (0,25)
0.005 (0,13)

Gauge Plane

0.004 (0,10)

Seating Plane

0.010 (0,25)   0°−8°

0.050 (1,27)
0.016 (0,40)

4040047−5/M   06/11

NOTES: A.   All linear dimensions are in inches (millimeters).
         B.   This drawing is subject to change without notice.
         C.   Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall
              not exceed 0.006 (0,15) each side.
         D.   Body width does not include interlead flash. Interlead flash shall not exceed 0.017 (0,43) each side.
         E.   Reference JEDEC MS−012 variation AB.

D (R−PDSO−G14)   PLASTIC SMALL OUTLINE

Example Board Layout
(Note C)

Stencil Openings
(Note D)

12x1,27

14x0,55

12x1,27

14x1,50

5,40

5,40

Example
Non Soldermask Defined Pad

Example
Pad Geometry
(See Note C)

0,60

1,55

Example
Solder Mask Opening
(See Note E)

0.07
All Around

4211283−3/E 08/12

NOTES: A. All linear dimensions are in millimeters.
          B. This drawing is subject to change without notice.
          C. Publication IPC−7351 is recommended for alternate designs.
          D. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should
              contact their board assembly site for stencil design recommendations. Refer to IPC−7525 for other stencil recommendations.
          E. Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.

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